

#### Final datasheet

#### XHP™2 module with CoolSiC™ Trench MOSFET and NTC / pre-applied thermal interface material

#### **Features**

- · Electrical features
  - V<sub>DSS</sub> = 2300 V
  - $-I_{DN} = 2000 A / I_{DRM} = 4000 A$
  - High current density
  - Low inductive design
  - Low switching losses
  - $T_{vj,op} = 175^{\circ}C$
- Mechanical features
  - Substrate for low thermal resistance
  - Copper base plate
  - High creepage and clearance distances
  - High power density
  - Package with CTI > 600
  - Pre-applied thermal interface material

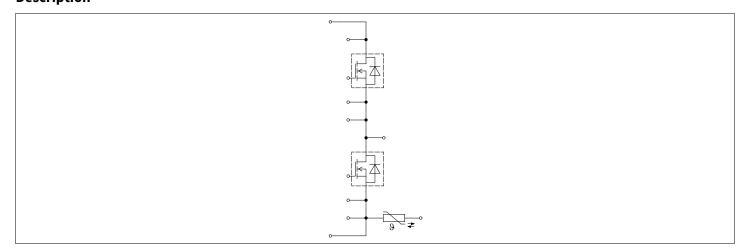
#### **Potential applications**

- · Central inverter
- Wind power generation
- · Energy storage systems
- Industrial drives
- · Traction drives
- DC/DC converter
- High-power converters
- High-frequency switching application

#### **Product validation**

• Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

#### **Description**





# XHP™2 module





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## XHP™2 module

1 Package



# 1 Package

### Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V <sub>ISOL</sub>	RMS, f = 50 Hz, t = 1 min	4.0	kV
Material of module baseplate			Cu	
Comparative tracking index	СТІ		> 600	

#### Table 2 Characteristic values

Parameter	Symbol	Note or test condition			Values		
				Min.	Тур.	Max.	
Stray inductance module	L <sub>sCE</sub>				10		nH
Module lead resistance, terminals - chip	R <sub>CC'+EE'</sub>	T <sub>H</sub> = 25 °C, per switch	「 <sub>H</sub> = 25 °C, per switch		0.4		mΩ
Storage temperature	$T_{\rm stg}$			-40		150	°C
Maximum baseplate operation temperature	$T_{BPmax}$					150	°C
Mounting torque for module mounting	М	- Mounting according to valid application note	M6, Screw	3		6	Nm
Terminal connection	М	- Mounting according to	M3, Screw	0.9		1.1	Nm
torque		valid application note	M8, Screw	8		10	
Weight	G		•		1020		g

### 2 MOSFET Inverter

#### Table 3 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	$V_{\rm DSS}$		T <sub>vj</sub> = 25 °C	2300	V
Implemented drain current	I <sub>DN</sub>			2000	Α
Continuous DC drain current	I <sub>DDC</sub>	$T_{\rm vj} = 175 ^{\circ}\text{C}, V_{\rm GS} = 15 ^{\circ}\text{V}$	T <sub>H</sub> = 45 °C	1185	A
Repetitive peak drain current	I <sub>DRM</sub>	verified by design, t <sub>p</sub> limited by T <sub>vjmax</sub>		4000	А
Gate-source voltage, max. transient voltage	$V_{GS}$	D < 0.01		-10/23	V
Gate-source voltage, max. static voltage	V <sub>GS</sub>			-7/20	V

# XHP™2 module

2 MOSFET Inverter



#### Table 4 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
On-state gate voltage	V <sub>GS(on)</sub>		1518	V
Off-state gate voltage	V <sub>GS(off)</sub>		-5	V

#### Table 5 Characteristic values

Parameter	Symbol	Note or test condition			Values		Unit
				Min.	Тур.	Max.	
Drain-source on-resistance	R <sub>DS(on)</sub>	I <sub>D</sub> = 2000 A	V <sub>GS</sub> = 15 V, T <sub>vj</sub> = 25 °C		0.95	1.19	mΩ
			V <sub>GS</sub> = 15 V, T <sub>vj</sub> = 125 °C		1.7	2.13	
			V <sub>GS</sub> = 15 V, T <sub>vj</sub> = 175 °C		2.3 2.88		
Gate threshold voltage	V <sub>GS(th)</sub>	$I_D$ = 900 mA, $V_{DS}$ = $V_{GS}$ , $T_{vj}$ after 1ms pulse at $V_{GS}$ = +		3.45	4.2	5.15	V
Total gate charge	Q <sub>G</sub>	$V_{\rm DD}$ =1500 V, $V_{\rm GS}$ = -5/15 V,	T <sub>vj</sub> = 25 °C		5.3		μC
Internal gate resistor	R <sub>Gint</sub>	T <sub>vj</sub> = 25 °C			1.1		Ω
Input capacitance	C <sub>ISS</sub>	$f = 100 \text{ kHz}, V_{DS} = 1500 \text{ V},$ $V_{GS} = 0 \text{ V}$	T <sub>vj</sub> = 25 °C		190		nF
Output capacitance	C <sub>OSS</sub>	$f = 100 \text{ kHz}, V_{DS} = 1500 \text{ V},$ $V_{GS} = 0 \text{ V}$	T <sub>vj</sub> = 25 °C		4.1		nF
Reverse transfer capacitance	C <sub>rss</sub>	$f = 100 \text{ kHz}, V_{DS} = 1500 \text{ V},$ $V_{GS} = 0 \text{ V}$	T <sub>vj</sub> = 25 °C		0.2		nF
C <sub>OSS</sub> stored energy	E <sub>OSS</sub>	$V_{\rm DS}$ = 1500 V, $V_{\rm GS}$ = -5/15 V	, T <sub>vj</sub> = 25 °C		5.8		mJ
Drain-source leakage current	I <sub>DSS</sub>	$V_{\rm DS}$ = 2300 V, $V_{\rm GS}$ = -5 V	T <sub>vj</sub> = 25 °C			930	μA
Gate-source leakage current	I <sub>GSS</sub>	$V_{\rm DS} = 0 \text{ V}, T_{\rm vj} = 25 ^{\circ}\text{C}$	V <sub>GS</sub> = 20 V			3200	nA
Turn-on delay time	t <sub>d on</sub>	$I_{\rm D} = 2000  \text{A}, R_{\rm Gon} = 0.1  \Omega,$	T <sub>vj</sub> = 25 °C		225		ns
(inductive load)		$V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V},$	T <sub>vj</sub> = 125 °C		215		
		$t_{\text{dead}} = 3000 \text{ ns}, 0.1 \text{ V}_{\text{GS}}$ to 0.1 I <sub>D</sub>	T <sub>vj</sub> = 175 °C		215		
Rise time (inductive load)	t <sub>r</sub>	$I_{\rm D} = 2000  \text{A}, R_{\rm Gon} = 0.1  \Omega,$	T <sub>vj</sub> = 25 °C		100		ns
		$V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V},$	T <sub>vj</sub> = 125 °C		100		
		$t_{\text{dead}} = 3000 \text{ ns}, 0.1 \text{ I}_{\text{D}} \text{ to}$ 0.9 I <sub>D</sub>	T <sub>vj</sub> = 175 °C		105		

(table continues...)

#### XHP™2 module

3 Body diode (MOSFET Inverter)



# Table 5 (continued) Characteristic values

Parameter	Symbol	Note or test condition			Values		Unit
				Min.	Тур.	Max.	
Turn-off delay time	t <sub>d off</sub>	$I_{\rm D} = 2000  \text{A}, R_{\rm Goff} = 1  \Omega,$	T <sub>vj</sub> = 25 °C		375		ns
(inductive load)		$V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V}, 0.9 \text{ V}_{GS} \text{ to}$	T <sub>vj</sub> = 125 °C		420		
		0.9 I <sub>D</sub>	T <sub>vj</sub> = 175 °C		450		
Fall time (inductive load)	t <sub>f</sub>	$I_{\rm D} = 2000  \text{A}, R_{\rm Goff} = 1  \Omega,$	T <sub>vj</sub> = 25 °C		105		ns
		$V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V}, 0.9 \text{ I}_{D} \text{ to } 0.1$	T <sub>vj</sub> = 125 °C		130		
		I <sub>D</sub>	T <sub>vj</sub> = 175 °C		145		
Turn-on time (resistive load)	t <sub>on_R</sub>	$I_{\rm D} = 500 \text{ A}, V_{\rm DD} = 2000 \text{ V},$ $V_{\rm GS} = -5/15 \text{ V},$ $R_{\rm Gon} = 0.1 \Omega$	T <sub>vj</sub> = 25 °C	625.00			ns
Turn-on energy loss per pulse	E <sub>on</sub>	/ - 14 pH // - E/1E//	T <sub>vj</sub> = 25 °C		410		mJ
			T <sub>vj</sub> = 125 °C		540		
		$16.3 \text{ kA/µs} (T_{\text{vj}} = 175 \text{ °C}),$ $t_{\text{dead}} = 3000 \text{ ns}$	T <sub>vj</sub> = 175 °C		640		
Turn-on energy loss per	E <sub>on,o</sub>	´	<i>T</i> <sub>vj</sub> = 25 °C		390		mJ
pulse, optimized			T <sub>vj</sub> = 125 °C		410		
		15.2 kA/ $\mu$ s ( $T_{vj}$ = 175 °C), $t_{dead}$ = 500 ns	T <sub>vj</sub> = 175 °C		470		
Turn-off energy loss per	E <sub>off</sub>	$I_{\rm D}$ = 2000 A, $V_{\rm DD}$ = 1500 V,	T <sub>vj</sub> = 25 °C		330		mJ
pulse		$L_{\sigma} = 14 \text{ nH}, V_{GS} = -5/15 \text{ V},$ $R_{Goff} = 1 \Omega, \text{ dv/dt} = 10.8$	T <sub>vj</sub> = 125 °C		370		
		$kV/\mu s (T_{vj} = 175 °C)$	T <sub>vj</sub> = 175 °C		400		
SC data	I <sub>SC</sub>	$V_{GS} = -5/15 \text{ V},$ $V_{DD} = 1500 \text{ V}, \text{V}_{DSmax} = \text{V}_{DSS} - \text{L}_{SDS} * \text{di/dt}$	$t_{\rm P} \le 3 \mu{\rm s},$ $T_{\rm vj} = 175 ^{\circ}{\rm C}$		12000		A
Thermal resistance, junction to heat sink	R <sub>thJH</sub>	per MOSFET, Valid with IF Thermal Interface Materi				33	K/kW
Temperature under switching conditions	T <sub>vj op</sub>			-40		175	°C

# 3 Body diode (MOSFET Inverter)

#### Table 6 Maximum rated values

Parameter	Symbol	Note or test condition	Note or test condition		
DC body diode forward current	I <sub>SD</sub>	$T_{\rm vj}$ = 175 °C, $V_{\rm GS}$ = -5 V	T <sub>H</sub> = 45 °C	975	А
I <sup>2</sup> t - value	l <sup>2</sup> t	$V_{\rm DS} = 0 \text{ V}, V_{\rm GS} = -5 \text{ V},$ $t_{\rm P} = 10 \text{ ms}$	T <sub>vj</sub> = 125 °C	600	kA <sup>2</sup> s
		$t_{\rm P}$ = 10 ms	T <sub>vj</sub> = 175 °C	500	

### XHP™2 module

4 NTC-Thermistor



#### Table 7 Characteristic values

Parameter	Symbol	Note or test condition			Values		Unit
				Min.	Тур.	Max.	
Forward voltage	V <sub>SD</sub>	$I_{SD} = 2000 \text{ A}, V_{GS} = -5 \text{ V}$	T <sub>vj</sub> = 25 °C		5	6.25	V
			T <sub>vj</sub> = 125 °C		4.4	5.5	
			T <sub>vj</sub> = 175 °C		4.2	5.25	
Reverse recovery energy	E <sub>rec</sub>	$I_{SD} = 2000 \text{ A, di}_{s}/\text{dt} =$	T <sub>vj</sub> = 25 °C		5.8		mJ
	V <sub>DD</sub>	16.3 kA/ $\mu$ s ( $T_{vj}$ = 175 °C), $V_{DD}$ = 1500 V, $V_{GS}$ = -5/15 V, $t_{dead}$ = 3000 ns	T <sub>vj</sub> = 125 °C		39.2		
			T <sub>vj</sub> = 175 °C		64.1		
Reverse recovery energy,	very energy, $E_{\text{rec,o}}$ $I_{\text{SD}} = 2000  R$	$I_{SD} = 2000 \text{ A, di}_{s}/\text{dt} =$	T <sub>vj</sub> = 25 °C		5.8		mJ
optimized		15.2 kA/µs (T <sub>vj</sub> = 175 °C), V <sub>DD</sub> = 1500 V,	T <sub>vj</sub> = 125 °C		11.8		
		$V_{GS} = -5/15 \text{ V},$ $t_{dead} = 500 \text{ ns}$	T <sub>vj</sub> = 175 °C		19.6		

# 4 NTC-Thermistor

#### Table 8 Characteristic values

Parameter	Symbol	Symbol Note or test condition		Values		
			Min.	Тур.	Max.	
Rated resistance	R <sub>25</sub>	T <sub>NTC</sub> = 25 °C		5		kΩ
Deviation of R <sub>100</sub>	∆R/R	$T_{\rm NTC}$ = 100 °C, $R_{100}$ = 493 $\Omega$	-5		5	%
Power dissipation	P <sub>25</sub>	T <sub>NTC</sub> = 25 °C			20	mW
B-value	B <sub>25/50</sub>	$R_2 = R_{25} \exp[B_{25/50}(1/T_2-1/(298,15 \text{ K}))]$		3375		K
B-value	B <sub>25/80</sub>	$R_2 = R_{25} \exp[B_{25/80}(1/T_2-1/(298,15 \text{ K}))]$		3411		К
B-value	B <sub>25/100</sub>	$R_2 = R_{25} \exp[B_{25/100}(1/T_2-1/(298,15 \text{ K}))]$		3433		K

**Note**: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4

5 Characteristics diagrams

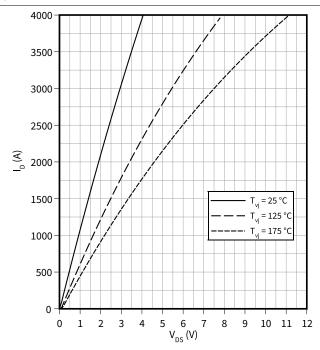


# **5** Characteristics diagrams

### **Output characteristic (typical), MOSFET Inverter**

 $I_D = f(V_{DS})$ 

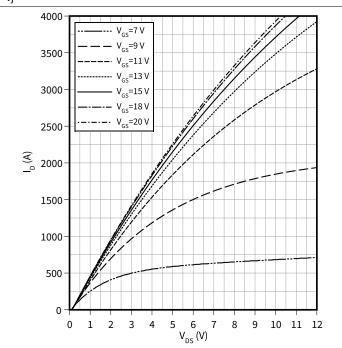
 $V_{GS} = 15 V$ 



### Output characteristic field (typical), MOSFET Inverter

 $I_D = f(V_{DS})$ 

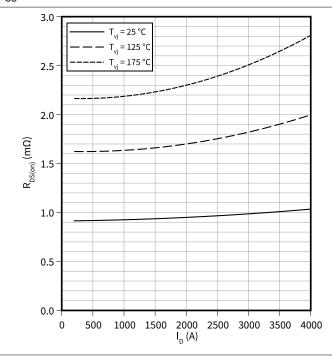
T<sub>vj</sub> = 175 °C



### Drain source on-resistance (typical), MOSFET Inverter

 $R_{DS(on)} = f(I_D)$ 

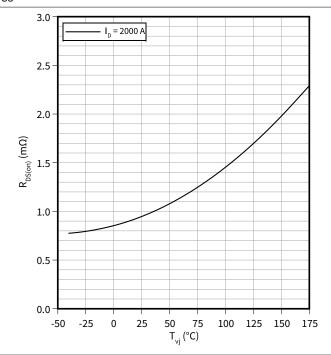
 $V_{GS} = 15 V$ 



#### Drain source on-resistance (typical), MOSFET Inverter

 $R_{DS(on)} = f(T_{vj})$ 

 $V_{GS} = 15 V$ 



#### XHP™2 module

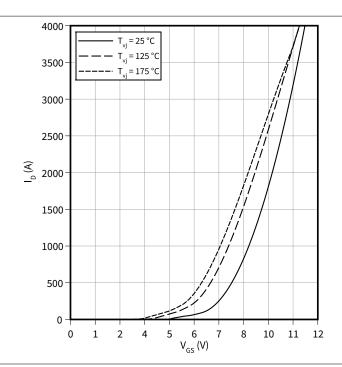
5 Characteristics diagrams



## Transfer characteristic (typical), MOSFET Inverter

$$I_D = f(V_{GS})$$

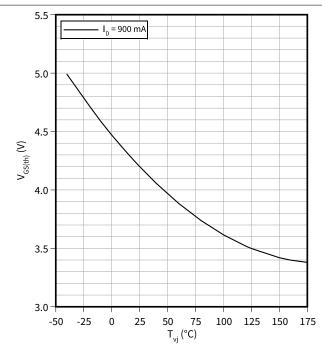
$$V_{DS} = 20 V$$



# **Gate-source threshold voltage (typical), MOSFET Inverter**

$$V_{\mathsf{GS}(\mathsf{th})} = \mathsf{f}(\mathsf{T}_{\mathsf{v}\mathsf{j}})$$

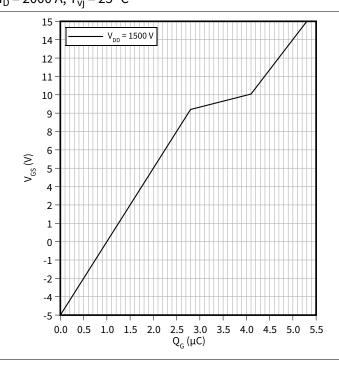
$$V_{GS} = V_{DS}$$



# Gate charge characteristic (typical), MOSFET Inverter

$$V_{GS} = f(Q_G)$$

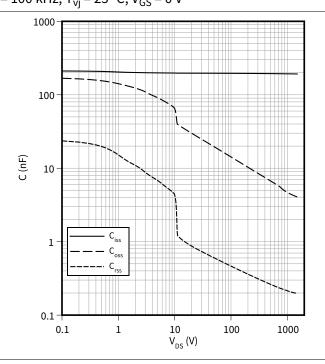
$$I_D = 2000 \text{ A}, T_{vj} = 25 \,^{\circ}\text{C}$$



# Capacity characteristic (typical), MOSFET Inverter

$$C = f(V_{DS})$$

$$f = 100 \text{ kHz}, T_{vj} = 25 \,^{\circ}\text{C}, V_{GS} = 0 \text{ V}$$



#### XHP™2 module

5 Characteristics diagrams



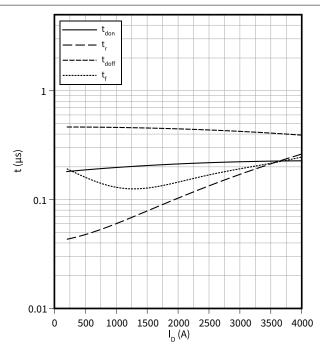
# Switching times (typical), MOSFET Inverter

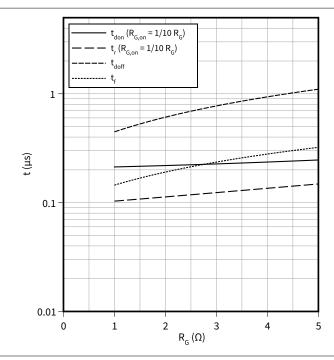
 $t = f(I_D)$ 

 $R_{Goff}$  = 1  $\Omega,\,R_{Gon}$  = 0.1  $\Omega,\,V_{DD}$  = 1500 V,  $T_{vj}$  = 175 °C,  $V_{GS}$  = -5/15 V

# Switching times (typical), MOSFET Inverter $t = f(R_G)$

 $V_{DD}$  = 1500 V,  $I_{D}$  = 2000 A,  $T_{vj}$  = 175 °C,  $V_{GS}$  = -5/15 V

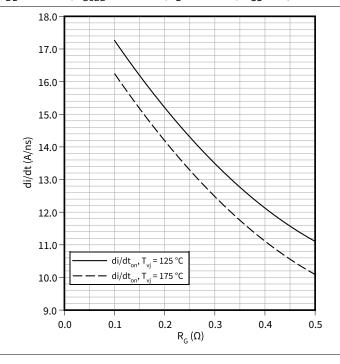




# Current slope (typical), MOSFET Inverter

 $di/dt = f(R_G)$ 

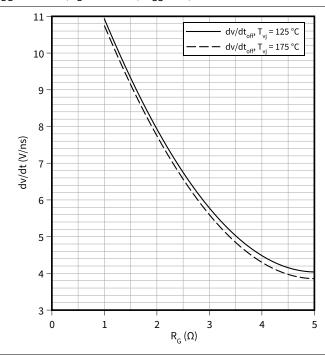
 $V_{DD}$  = 1500 V,  $t_{dead}$  = 3000 ns,  $I_{D}$  = 2000 A,  $V_{GS}$  = -5/15 V



### Voltage slope (typical), MOSFET Inverter

 $dv/dt = f(R_G)$ 

 $V_{DD} = 1500 \text{ V}, I_D = 2000 \text{ A}, V_{GS} = -5/15 \text{ V}$ 



#### XHP™2 module

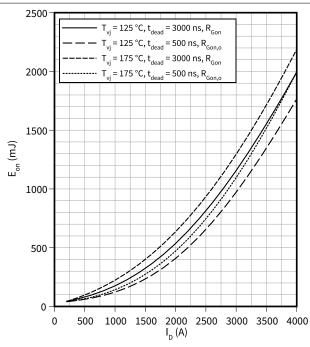
5 Characteristics diagrams



## Switching losses (typical), MOSFET Inverter

$$E_{on} = f(I_D)$$

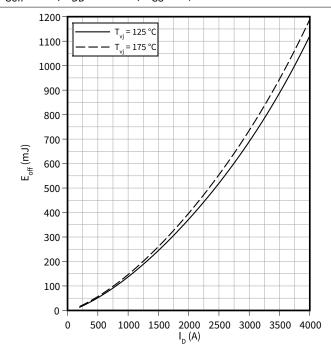
$$R_{Gon} = 0.1 \Omega$$
,  $V_{DD} = 1500 V$ ,  $R_{Gon,o} = 0.1 \Omega$ ,  $V_{GS} = 15/-5 V$ 



#### Switching losses (typical), MOSFET Inverter

$$E_{off} = f(I_D)$$

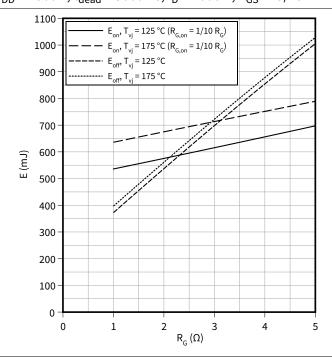
$$R_{Goff} = 1 \Omega$$
,  $V_{DD} = 1500 V$ ,  $V_{GS} = -5/15 V$ 



## Switching losses (typical), MOSFET Inverter

 $E = f(R_G)$ 

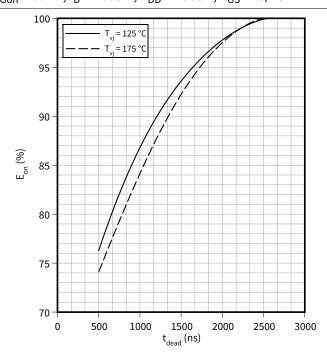
$$V_{DD} = 1500 \text{ V}, t_{dead} = 3000 \text{ ns}, I_{D} = 2000 \text{ A}, V_{GS} = -5/15 \text{ V}$$



## Switching losses (typical), MOSFET Inverter

$$E_{on} = f(t_{dead})$$

$$R_{Gon} = 0.1 \Omega$$
,  $I_D = 2000 A$ ,  $V_{DD} = 1500 V$ ,  $V_{GS} = -5/15 V$ 



#### XHP™2 module

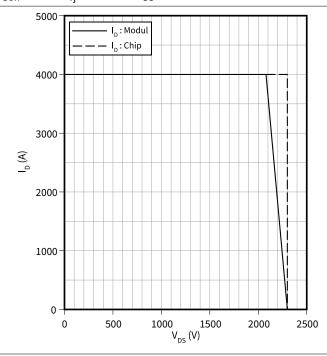




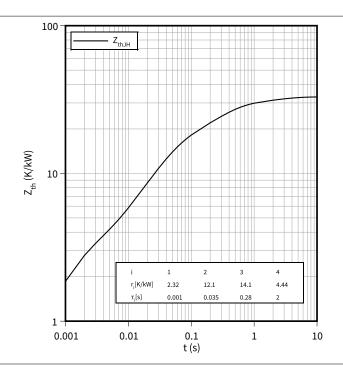
# Reverse bias safe operating area (RBSOA), MOSFET Inverter

 $I_D = f(V_{DS})$ 

$$R_{Goff} = 1 \Omega$$
,  $T_{vj} = 175 \,^{\circ}\text{C}$ ,  $V_{GS} = -5/15 \,^{\circ}\text{V}$ 



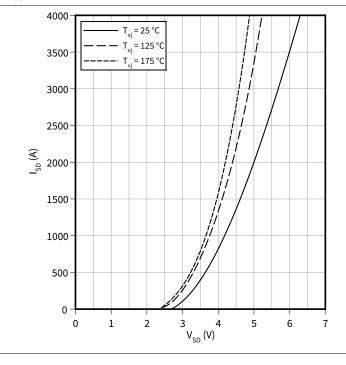
# Transient thermal impedance, MOSFET Inverter $Z_{th} = f(t)$



# Forward characteristic body diode (typical), MOSFET Inverter

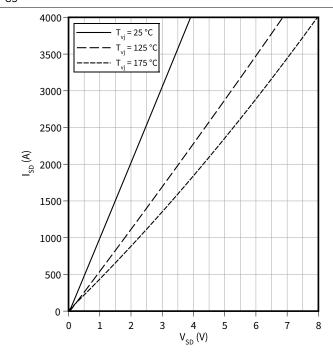
 $I_{SD} = f(V_{SD})$ 

$$V_{GS} = -5 V$$



# Forward characteristic body diode (typical), MOSFET Inverter

 $I_{SD} = f(V_{SD})$ 



#### XHP™2 module

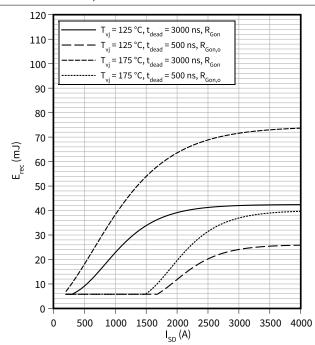
5 Characteristics diagrams



# Switching losses body diode (typical), MOSFET Inverter

 $E_{rec} = f(I_{SD})$ 

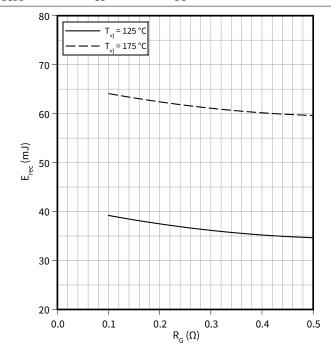
 $R_{Gon} = 0.1 \Omega$ ,  $R_{Gon,o} = 0.1 \Omega$ ,  $V_{DD} = 1500 V$ 



# Switching losses body diode (typical), MOSFET Inverter

 $E_{rec} = f(R_G)$ 

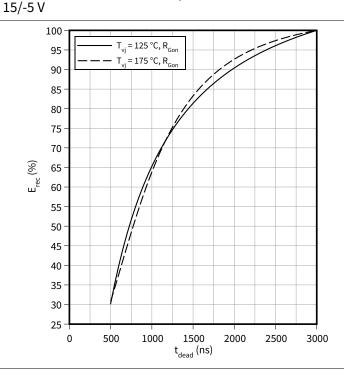
 $|t_{dead}| = 3000 \text{ ns}, t_{SD}| = 2000 \text{ A}, t_{DD}| = 1500 \text{ V}$ 



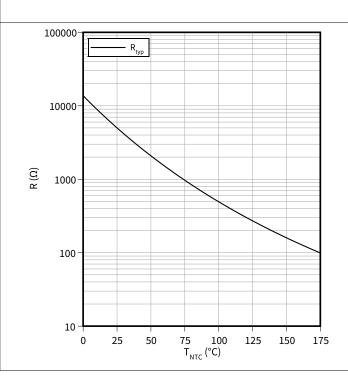
# Switching losses body diode (typical), MOSFET Inverter

 $E_{rec} = f(t_{dead})$ 

 $R_{Gon} = 0.1 \Omega$ ,  $I_D = 2000 A$ ,  $R_{Gon,o} = 0.1 \Omega$ ,  $V_{DD} = 1500 V$ ,  $V_{GS} = 15 / 5 V$ 



# Temperature characteristic (typical), NTC-Thermistor $R = f(T_{NTC})$



FF1000UXTR23T2M1P XHP™2 module 6 Circuit diagram



#### **Circuit diagram** 6

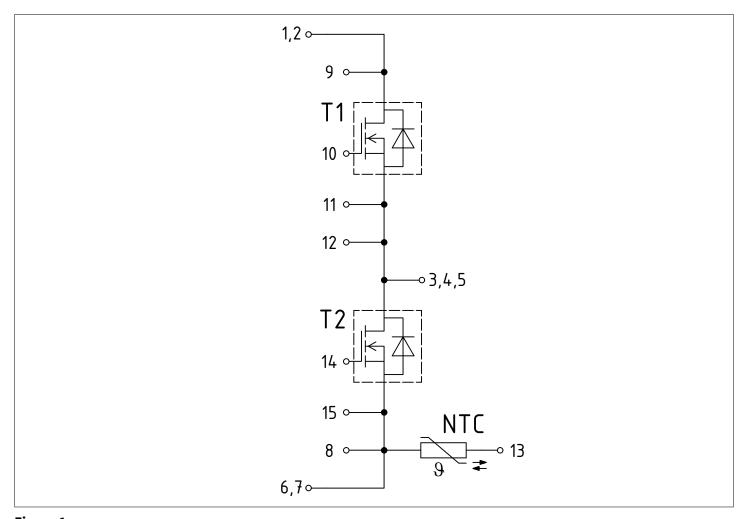


Figure 1

7 Package outlines



# 7 Package outlines

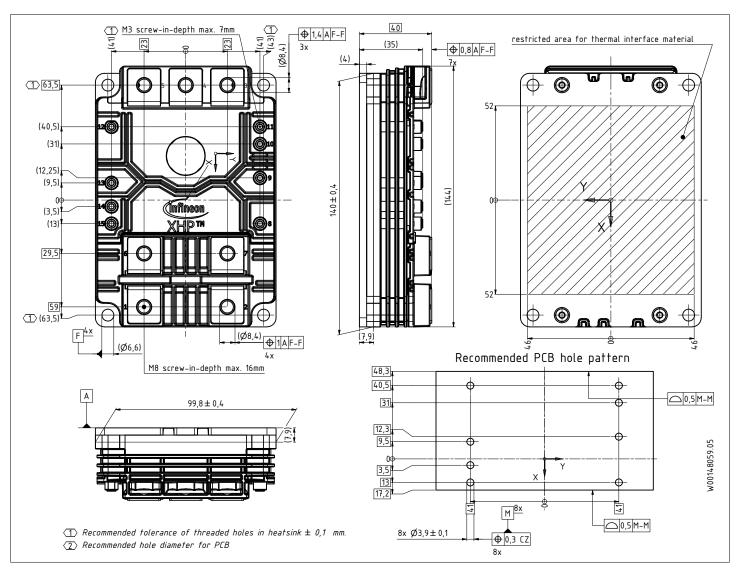


Figure 2

## XHP™2 module

8 Module label code



# 8 Module label code

Code format	Data Matrix		Barcode (	Code128
Encoding	ASCII text		Code Set	A
Symbol size	16x16		23 digits	
Standard	IEC24720 and IEC16022		IEC8859-1	
Code content	ContentDigitModule serial number1 - 5Module material number6 - 11Production order number12 - 19Date code (production year)20 - 21Date code (production week)22 - 23			Example 71549 142846 55054991 15 30
Example	71549142846550549911530			#6550549911530

Figure 3

# XHP™2 module

Revision history



# **Revision history**

Document revision	Date of release	Description of changes
0.10	2025-06-08	Preliminary datasheet
1.00	2025-07-07	Final datasheet

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